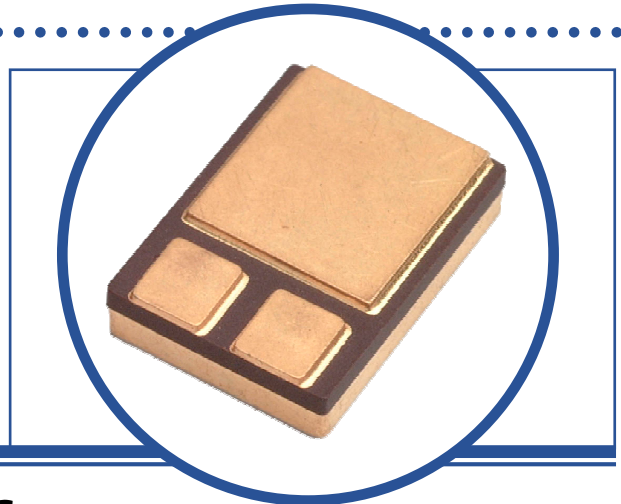


# P-CHANNEL POWER MOSFET

## IRFN5210

- Low  $R_{DS(on)}$  Power MOSFET Transistor, Fully Avalanche Rated
- Hermetic Ceramic Surface Mount package
- Designed For Fast Switching Applications
- Screening Options Available



### ABSOLUTE MAXIMUM RATINGS ( $T_C = 25^\circ\text{C}$ unless otherwise stated)

$V_{DS}$	Drain – Source Voltage		-100V
$V_{GS}$	Gate – Source Voltage		$\pm 20\text{V}$
$I_D$	Continuous Drain Current	$T_C = 25^\circ\text{C}$	-34A
$I_D$	Continuous Drain Current	$T_C = 100^\circ\text{C}$	-24A
$I_{DM}$	Pulsed Drain Current <sup>(1)</sup>		-120A
$P_D$	Total Power Dissipation at	$T_C = 25^\circ\text{C}$	150W
	Derate Above $25^\circ\text{C}$		1.0W/ $^\circ\text{C}$
$E_{AS}$	Single Pulse Avalanche Energy <sup>(2)</sup>		780mJ
dv/dt	Peak Diode Recovery <sup>(3)</sup>		-5.0V/ns
$T_J$	Junction Temperature Range		-55 to $+175^\circ\text{C}$
$T_{stg}$	Storage Temperature Range		-55 to $+175^\circ\text{C}$

### THERMAL PROPERTIES

Symbols	Parameters	Max.	Units
$R_{\theta JC}$	Thermal Resistance, Junction To Case	1.0	$^\circ\text{C/W}$

#### Notes

- (1) Repetitive Rating: Pulse width limited by maximum junction temperature
- (2) @  $V_{DD} = -25\text{V}$ ,  $L = 3.1\text{mH}$ , Peak  $I_L = -21\text{A}$ , Starting  $T_J = 25^\circ\text{C}$ ,  $R_G = 25\Omega$
- (3) @  $I_{SD} \leq -21\text{A}$ ,  $di/dt \leq -480\text{A}/\mu\text{s}$ ,  $V_{DD} \leq -100\text{V}$ ,  $T_J \leq 175^\circ\text{C}$
- (4) Pulse Width  $\leq 300\mu\text{s}$ ,  $\delta \leq 2\%$

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## ELECTRICAL CHARACTERISTICS (T<sub>C</sub> = 25°C unless otherwise stated)

Symbols	Parameters	Test Conditions	Min.	Typ	Max.	Units
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0 I <sub>D</sub> = -250μA	-100			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Temperature Coefficient of Breakdown Voltage	Reference to 25°C I <sub>D</sub> = -1.0mA		-0.11		V/°C
R <sub>DS(on)</sub>	Static Drain-Source On-State Resistance	V <sub>GS</sub> = -10V I <sub>D</sub> = -24A <sup>(4)</sup>			0.06	Ω
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> I <sub>D</sub> = -250μA	-2		-4	V
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> = -50V I <sub>DS</sub> = -21A <sup>(4)</sup>	10			S(Ω)
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>GS</sub> = 0 V <sub>DS</sub> = -100V			-25	μA
		V <sub>GS</sub> = 0 V <sub>DS</sub> = -80V T <sub>J</sub> = 150°C			-250	
I <sub>GSS</sub>	Forward Gate-Source Leakage	V <sub>GS</sub> = 20V			100	nA
I <sub>GSS</sub>	Reverse Gate-Source Leakage	V <sub>GS</sub> = -20V			-100	

## DYNAMIC CHARACTERISTICS

C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> = 0		2700		pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> = 25V		790		
C <sub>rss</sub>	Reverse Transfer Capacitance	f = 1.0MHz		450		
Q <sub>g</sub>	Total Gate Charge	V <sub>GS</sub> = -10V			180	nC
Q <sub>gs</sub>	Gate-Source Charge	I <sub>D</sub> = -21A			25	
Q <sub>gd</sub>	Gate-Drain Charge	V <sub>DS</sub> = -80V			97	
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = -50V		17		ns
t <sub>r</sub>	Rise Time	I <sub>D</sub> = -21A		86		
t <sub>d(off)</sub>	Turn-Off Delay Time			79		
t <sub>f</sub>	Fall Time	R <sub>G</sub> = 2.5Ω R <sub>D</sub> = 2.4Ω		81		

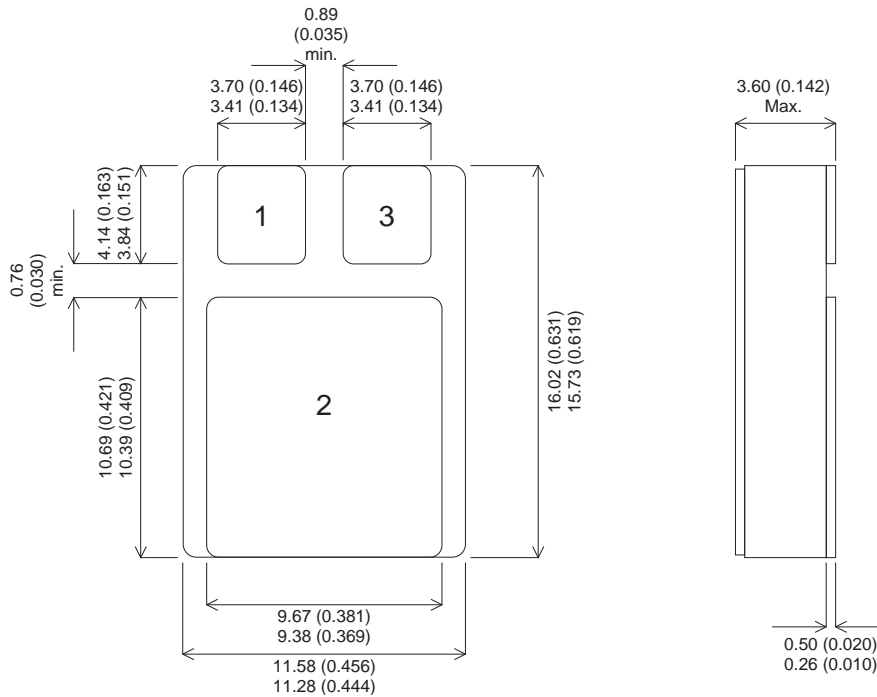
## SOURCE-DRAIN DIODE CHARACTERISTICS

I <sub>S</sub>	Continuous Source Current				-34	A
I <sub>SM</sub>	Pulse Source Current <sup>(1)</sup>				-120	
V <sub>SD</sub>	Diode Forward Voltage	I <sub>S</sub> = -24A T <sub>J</sub> = 25°C V <sub>GS</sub> = 0			1.6	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>S</sub> = -21A T <sub>J</sub> = 25°C		170	260	ns
Q <sub>rr</sub>	Reverse Recovery Charge	V <sub>DD</sub> ≤ 50V di/dt = 100A/μs <sup>(4)</sup>		1.2	1.8	μC

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## MECHANICAL DATA

Dimensions in mm (inches)



### SMD1 (TO-276AB)

#### Underside View

Pad 1 – Source

Pad 2 – Drain

Pad 3 – Gate

#### Note

IRF5210SMD also available with pads 1 and 3 reversed.